



Call for papers
Shanghai World Expo Exhibition & Convention Center
April 25-26
Shanghai, China

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FOR IMMEDIATE RELEASE

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Greetings to our Valued SMTA Speakers and Industry Colleagues



In conjunction with



Call for Papers 2017 for the Technology Conference

The SMTA China cordially invites you to participate in **SMTA China East Conference** located in **Shanghai 2017**. This event, held in conjunction with NEPCON China 2017, will as usual address the industry's most pressing issues in electronics assembly/ manufacturing, industry/ technology roadmap, business focus, advanced packaging, practical skill development, emerging technologies, and lead-free & reliability.



You are invited to submit a paper to the electronic industry's premier forum on the manufacture of electronic products utilizing surface mount and related technologies. Papers are sought in the following key technology tracks:

Advanced Packaging/Components:

2.5/3D Packaging and Integration

BGA/CSP

Biomedical Packaging

Component Storage

Connector Technology

Copper Pillars

Copper Wire Bonding

Diffusion Bonding

Embedded and Miniature Passives

Environmental Testing

Failure Analysis Techniques

Flip Chip

High Temperature Packaging

Lead Finishes

Magnetic Soldering

MEMS and Sensors

Moisture Sensitive Devices (MSD)

Package on Package (PoP)

Photonics

Photovoltaics and Solar

Reliability

Silver Wire-bonding

Stacked Die

System in Package (SiP)

Through Silicon Vias (TSVs)

Tin Whiskers

Wafer Level Packaging (WLP)

Assembly:

01005/03015 Components/Assembly

3D Board Assembly

Additive Manufacturing

SMT Adhesives

Alternate Solder Alloys

BGA/CSP Assembly
Bottom Terminated Components
Cavity Board Assembly
Cleaning, Conformal Coating and Potting
Connector Assembly to PCB
DFX/Design for Six Sigma
Direct Chip Attach to PCB (DCA)
Dispensing & Underfill
Epoxy Fluxes
Facility Layout
Halogen and Halogen-Free
Head on Pillow Defect/Warpage Induced Solder Joint Defects
High Melting Point Solder
Laser Soldering
Leadless Area Array Packages
Lead-Free Soldering/Reliability
Low Temperature Processing
Low Volume/Prototype
Non-Wet Open (NWO) Defects
Package-on-Package Assembly
Part Obsolescence
Placement
Printing
Reflow Soldering/ Wave Soldering
Rework and Repair of QFNs (01005,
Leadless Components, PoP)
Rework Reliability
Robotic Soldering
Selective Soldering
Solder Jetting
Solder Paste/Solder Voids in Joints
Solderless Interconnections
Supplier Engineering
Thermo Compression Bonding
Underfill/ Corner Glue/ Other Polymeric Reinforcements
Vapor Phase Reflow
Yield Improvement

Business/Supply Chain:

Capacity Modeling
Conict Minerals
Contract Manufacturing
Counterfeit Parts
Doing Business in Overseas
Environmental Issues
Lean Manufacturing
Onshoring
Operations Management
Part Obsolescence
RoHS/REACH Compliance
Supplier Management
Technology Roadmaps

Emerging Technologies:

<= 0.3mm Pitch Area Array Technologies
3D Circuits
3D Printing & Design Rules
Advanced Packaging
Assembly to Flex Substrates
Assembly to Glass Substrates
Cavity Assembly
Consumer Applications
Embedded Active Technology
Embedded Passive Technology
Flexible Electronics
High Frequency
Jetting of Solder Pastes
LED Technology/Assembly/Reliability
MEMS/RF/MOEMS
Microsystems Packaging / Modular Microsystems
Nanomaterials
Nanotechnology, Materials, & Electronics
New Materials and Processes
Optoelectronics
Plastic 3D PCB to PCB Technology
Power or Thermal Management

Power Electronics
Printed Electronics Technology
Reliability of Nanodevices
Resin Reinforcement Solder Pastes
Sensors and Manufacturing
Smart Manufacturing Systems
Small Die Size Singulation
Solid State Lighting
Solar Technology
System in a Package
Thermal Interface Materials
Touch Screen Technologies
Virtual Prototyping
Wearable Electronics
Wireless Applications

Harsh Environment Applications

(Military, Aerospace, Automotive, Industrial, Oil & Gas):

Alternate Energy
Battery Prognostics
Components and Reliability
Copper Corrosion
COTS
High Lead Solder Replacement
High Temperature Electronics
Lead-free Issues
Non-Destructive Inspection
Micro-Computed Tomography
Multiphysics Modeling
Substrates and Finishes
Thermal Management
Tin Whiskers

PCB Technology:

Bio-Compatible Substrates
Black Pad and Surface Finish Defects
Conductive Anodic Filament (CAF)
Creep Corrosion



Embedded Passive/Active Components

Halogen Free

HDI

High Power PCBs

Micro-vias (including filled/unfilled)

Moisture Sensitivity

New Laminate Materials

New Surface Finishes & Solderability

Pad Cratering

Soldermask

Substrate Reliability

Process Control:

Acoustic Imaging (C-SAM)

Benefits of AOI & SPI

CIM


In-Circuit Test

Process Modeling

Software

Test Strategies

2D/3D X-Ray

	SMTA China East (NEPCON China)
Technology Conference 30 minutes pure technical papers presented 5 minutes for answering the question	25-26 April 2017

If you or your company wishes to share pertinent information with the highly qualified audience of **SMTA China** please submit your abstract to Peggy Chen by email to peggychen@smta.org.cn Please include your name, job title, company affiliation, and all pertinent contact information **as well as your choice of Technology Conference for your paper.**

You are invited to submit a paper to the electronic industry's premier forum on the manufacture of electronic products utilizing surface mount and related technologies. Papers are sought in the following key technology tracks:



SMTA China solicits technical papers for presentation in the **Technology Conference**. Inclusion in the Technology Conference requires strictly technical papers (**complimentary presentation slot for speakers**) subject to final acceptance by the Technical Advisory Committee of SMTA China. All papers including abstract and biography for inclusion in the Conference Proceedings requested in both **Chinese and English**. **All papers (powerpoint) must be in Chinese and shall be presented in Chinese or English with translator.**

Deadlines of Materials submission for the SMTA China East Conference:

Abstract and Speaker Bio(Chinese and English version) 20 January 2017
Bilingual Paper and Chinese version of PPT 28 February 2017

In order to appreciate the speakers of excellent information sharing, SMTA China would like to honor the best paper, and the speaker of best presentation, which award will be presented during the Annual Award Presentation which will be held at the venue of vendor conference in the afternnon of 25 April in Shanghai

Thank you for your support of SMTA China and we look forward to hearing from you.

Contact and Enquiry: Ms. Peggy Chen, Executive Administrator of SMTA China,
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2016年11月14日

尊敬的表面装贴技术协会演讲者和业内同行



同期举行于:



为高科技技术研讨会 2017 征集论文

中国 SMTA 诚意的邀请您参加 2017 年在上海举办的 SMTA 华东高科技会议。此次会议将与第二十七届中国国际电子生产设备暨微电子工业展联合举办，此次会议将涉及行业中最热门的话题，包括电子组装/制造，工业/技术路标，商业焦点，新兴技术，实践技能发展，和无铅及其可靠性。

征集电子制造表面装贴技术及科技方面的论文，论文题材涵盖以下关键技术：

先进封装及元件：

2.5/3D封装和集成

BGA/CSP

生物技术封装

元件存储

连接器技术

铜柱

铜线打线

扩散打线

嵌入及微型被动元件

环境测试

故障分析技术

倒装芯片

耐高温封装

引脚处理

磁力焊接

微型机电系统及传感器

湿度敏感器件

封装堆叠(PoP)

光子学

光伏太阳能

可靠性

银线打线

裸芯片堆叠

系统级封装

穿透硅通孔

锡须

晶圆级封装

装配:

01005/03015元件及装配

3D装配

增材制造

SMT粘胶

替代焊料合金

BGA/CSP装配

底部端子元件

空腔基板装配

清洗、敷型涂覆及注胶

基板联接装配

DFX和零缺陷设计

基板上芯片直装

点胶与底部填充胶

环氧树脂助焊剂

工厂设施布置

无卤与零卤素

头枕缺陷、翘曲相关锡点缺陷

高熔点焊料

激光焊接

无引脚阵平面列封装

无铅焊接及可靠性

低温焊接

小批量与原型机

无润湿空焊

封装堆叠装配

器件废除

贴装

印刷

回流焊接与波峰焊接

精密复杂器件返修

返修可靠性

机器人焊接

选择性焊接

喷涂式点锡膏

焊锡膏与焊点空洞

非焊接式互联

供应工程

热压打线

底部填充、边角固定及聚合物强化

汽相焊接

良率改善

商业与供应链：

产能模型

冲突矿产

合同制造

高仿器件

海外业务

环境问题

精益制造

在岸外包

营运管理

器件废除

RoHS/REACH合规

供应商管理

技术路线图

新兴技术：

$\leq 0.3\text{mm}$ 间距平面阵列技术

3D 电路

3D打印和设计规范

先进封装

柔性板装配

玻璃板装配

空腔板装配

消费电子

嵌入式主动技术

嵌入式被动技术

柔性电子

高频电子

焊锡膏喷涂

LED技术、装配和可靠性

微机电系统、微光机电系统及射频技术

微系统封装、微系统模组

纳米材料

纳米技术、材料和电子

新材料与制程

光电技术

塑料3D基板联接

功耗和散热管理

电源电子

印刷电子技术

纳米器件的可靠性

助焊剂增强型锡膏

传感器与制造

智能制造系统

小型芯片切单

固体照明

太阳能技术

系统级封装

热介质材料

触摸屏技术

虚拟原型机

可穿戴电子

无线电器

环保应用(军工、航天、汽车、工业、石油天然气):

替代能源

电池剩余电量估算

元件与可靠性

铜腐蚀

商用现货COTS

高铅焊料替代

耐高温电子

无铅问题

非破坏性检查

微断层造影技术

多物理场耦合分析模型

基材与表面处理

散热管理

锡须

基板技术：

生物相容基材

黑焊盘和表面处理缺陷

导电阳极丝 (CAF)

爬行腐蚀

嵌入式被动、主动元件

无卤

高密度集成HDI

高功率基板

微通孔(包括填充与非填充)

湿度敏感器件

新型层压板材料

新型表面处理和可靠性

焊盘坑裂

阻焊膜

基材可靠性

制程控制：

声学成像(C-SAM)

自动光学检查的效益

计算机集成制造(CIM)

ICT在线测试

工艺制程模型


软件

测试策略

2D/3D X光检查



中国 SMTA 为高科技技术研讨会中的演讲征集技术论文。高科技技术研讨会的技术论文主题及内容必须为纯技术论文，经由中国 SMTA 技术顾问委员会最终决定后，将被列入会议题目(高科技技术研讨会的演讲者无需缴付赞助费)。所有论文包括文章大纲和演讲者个人简介要求中文和英文刊登在技术论文集中。所有演讲（幻灯片形式的演讲稿）必须为中文并且以中文讲解或英文讲解配备翻译。

	华东高科技会议 (第二十七届中国国际电子生产设备暨微电子工业展)
高科技技术研讨会 30 分钟的论文演讲 5 分钟的现场问题回答	2017 年 4 月 25 日-26 日

如果您和您的公司希望与中国 SMTA 的会员及专业观众分享贵公司的有关信息，请发邮件提交您的文章大纲给 SMTA 行政主任陈蕙至 peggychen@smta.org.cn 并写上您的名字、工作头衔和公司的相关信息以及有关联系信息并且注明您的技术论文是投稿于高科技技术研讨会。

华东高科技技术研讨会提交材料的截止日期：

文章大纲和演讲者个人简介(中文和英文版本) **2017 年 1 月 20 日**
中文 / 英文的论文和中文的幻灯片形式的演讲稿 **2017 年 2 月 28 日**

为了感谢演讲者们优秀信息的分享，中国 SMTA 将于上海 4 月 25 日下午在设备技术研讨会的演讲现场举办的周年颁奖典礼上颁发最佳论文奖和最佳演讲奖。

感谢您支持中国 SMTA，期待您的消息。

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